

Claims

1 -16 (cancelled)

17. (Currently Amended) An apparatus for handling wafers, wherein the apparatus is configured to place said wafers from a wafer-holding cassette disposed on a loading station directly into a wafer processing vacuum chamber, and wherein said wafer processing vacuum chamber has a wafer holding device including a cooling plate and a heating plate, the apparatus for handling wafers comprising:

the cooling plate, the heating plate, and the loading station are arranged in a row one behind the other with the cooling plate in front of the heating plate;

an external handling device having grippers for transferring said wafers between said cassette and said wafer processing vacuum chamber, wherein said external handling device is disposed outside of said wafer processing vacuum chamber; and

an internal handling device disposed within said wafer processing vacuum chamber and is provided with a ~~transverse guide (11)~~ guide for lateral and vertical movement of said fork, said internal handling device having at least one fork arranged in a mount on said ~~transverse guide~~ guide for lateral and vertical movement of said fork to move with at least two degrees of freedom and arranged to interact with said grippers of said external handling device to directly receive a wafer therefrom, said fork being arranged to move said wafers between said cooling plate and said heating plate,

wherein said wafer-holding cassette disposed on a loading station is disposed outside of said vacuum chamber, wherein said cooling plate and said heating plate are disposed one in front of the other in said vacuum chamber, and wherein said internal and external

handling devices are configured to move said wafers from said wafer holding cassette outside of the vacuum chamber to the said cooling plate and said heating plate in said vacuum chamber and back, and wherein said chamber and said external handling device are surrounded by an enclosure, and wherein .

18. (Previously presented) Apparatus as specified in claim 17 wherein said fork is arranged to be movable under a placement location for said wafers on said wafer holding device.

19. (cancelled)

20. (cancelled)

21. (Previously presented) Apparatus as specified in claim 17 wherein there is provided a cooling device for cooling said internal handling device.

22. (Previously presented) Apparatus as specified in claim 17 wherein there are provided multiple heating and cooling plates arranged in a stack in said chamber.

23. (Cancelled)

24. (Cancelled)

25. (Previously presented) Apparatus as specified in claim 17 wherein said fork is arranged to be preheated.

26. (Previously presented) Apparatus as specified in claim 25 wherein said fork is arranged to contact said heating plate for said preheating.

27. (Cancelled)

28. (Previously presented) Apparatus as specified in claim 17 wherein there are provided multiple chambers arranged in a stack.

29. (Cancelled)

30. (Cancelled)

31. (Previously presented) Apparatus as specified in claim 17 wherein said enclosure is purged by gas at a low overpressure.